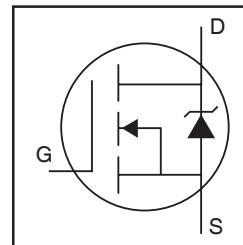


Applications

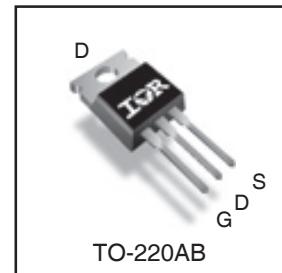
- High Efficiency Synchronous Rectification in SMPS
- Uninterruptible Power Supply
- High Speed Power Switching
- Hard Switched and High Frequency Circuits



V_{DSS}	100V
R_{DS(on)} typ.	3.7mΩ
max.	4.5mΩ
I_D (Silicon Limited)	180A ①
I_D (Package Limited)	120A

Benefits

- Improved Gate, Avalanche and Dynamic dv/dt Ruggedness
- Fully Characterized Capacitance and Avalanche SOA
- Enhanced body diode dV/dt and dl/dt Capability
- Lead Free
- RoHS Compliant, Halogen-Free



G	D	S
Gate	Drain	Source

Base Part Number	Package Type	Standard Pack		Orderable Part Number
		Form	Quantity	
IRFB4110PbF	TO-220	Tube	50	IRFB4110PbF

Absolute Maximum Ratings

Symbol	Parameter	Max.	Units
I _D @ T _C = 25°C	Continuous Drain Current, V _{GS} @ 10V (Silicon Limited)	180①	A
I _D @ T _C = 100°C	Continuous Drain Current, V _{GS} @ 10V (Silicon Limited)	130①	
I _D @ T _C = 25°C	Continuous Drain Current, V _{GS} @ 10V (Wire Bond Limited)	120	
I _{DM}	Pulsed Drain Current ②	670	
P _D @ T _C = 25°C	Maximum Power Dissipation	370	
	Linear Derating Factor	2.5	
V _{GS}	Gate-to-Source Voltage	± 20	V
dv/dt	Peak Diode Recovery ④	5.3	V/ns
T _J	Operating Junction and	-55 to + 175	°C
T _{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 seconds (1.6mm from case)	300	
	Mounting torque, 6-32 or M3 screw	10lb·in (1.1N·m)	

Avalanche Characteristics

E _{AS} (Thermally limited)	Single Pulse Avalanche Energy ③	190	mJ
I _{AR}	Avalanche Current ②	See Fig. 14, 15, 22a, 22b	A
E _{AR}	Repetitive Avalanche Energy ⑤		mJ

Thermal Resistance

Symbol	Parameter	Typ.	Max.	Units
R _{θJC}	Junction-to-Case ⑨	—	0.402	°C/W
R _{θCS}	Case-to-Sink, Flat Greased Surface	0.50	—	
R _{θJA}	Junction-to-Ambient ⑩	—	62	

Static @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	100	—	—	V	$V_{GS} = 0V, I_D = 250\mu\text{A}$
$\Delta V_{(\text{BR})\text{DSS}}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.108	—	V/ $^\circ\text{C}$	Reference to $25^\circ\text{C}, I_D = 5\text{mA}$ ②
$R_{DS(\text{on})}$	Static Drain-to-Source On-Resistance	—	3.7	4.5	m Ω	$V_{GS} = 10V, I_D = 75\text{A}$ ⑤
$V_{GS(\text{th})}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
I_{DSS}	Drain-to-Source Leakage Current	—	—	20	μA	$V_{DS} = 100V, V_{GS} = 0V$
		—	—	250	—	$V_{DS} = 100V, V_{GS} = 0V, T_J = 125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS} = 20V$
	Gate-to-Source Reverse Leakage	—	—	-100	—	$V_{GS} = -20V$

Dynamic @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

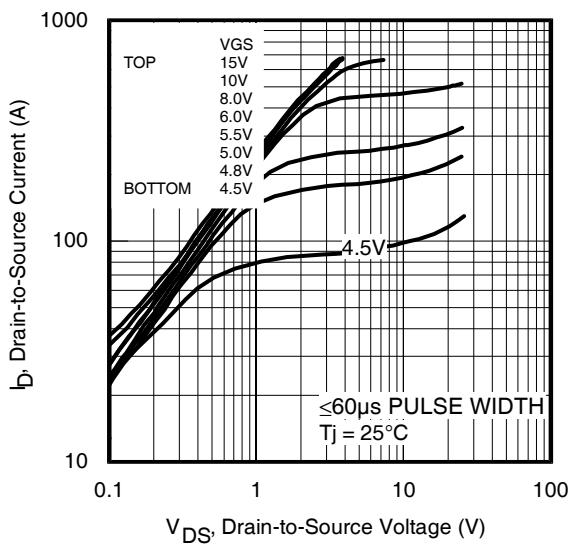
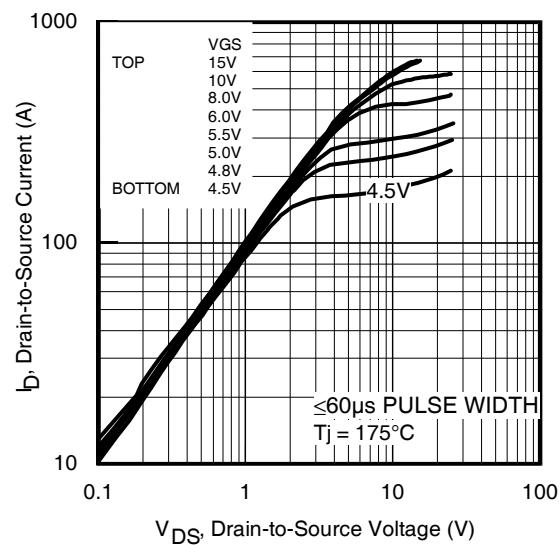
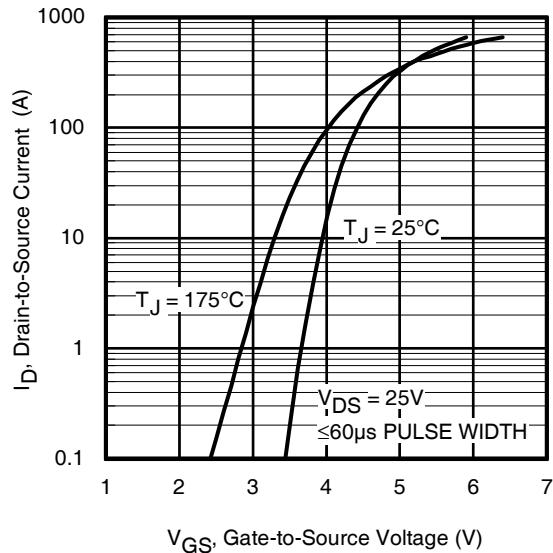
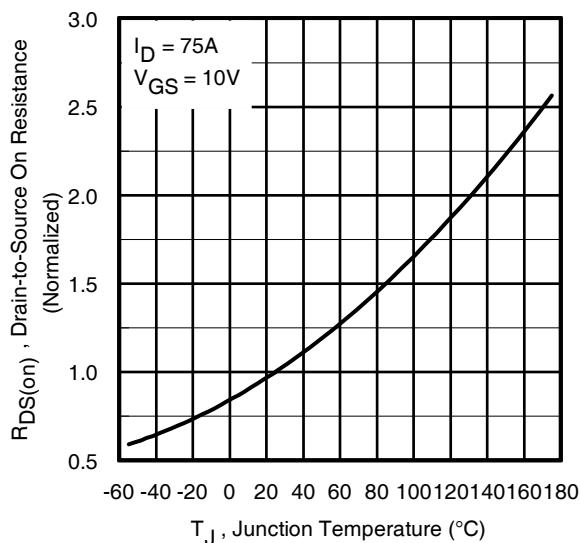
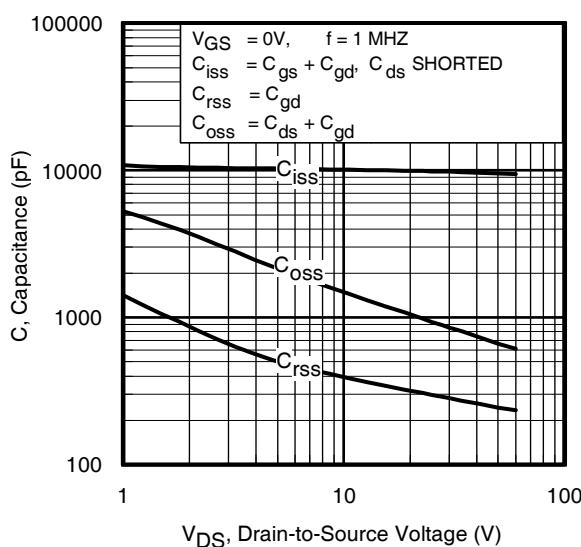
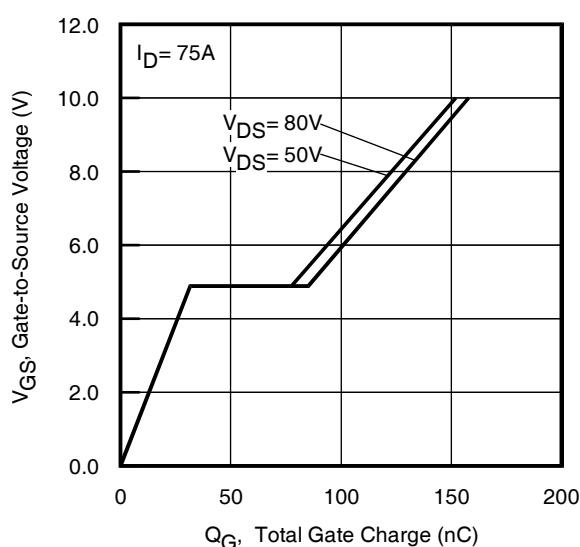
Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
g_{fs}	Forward Transconductance	160	—	—	S	$V_{DS} = 50V, I_D = 75\text{A}$
Q_g	Total Gate Charge	—	150	210	nC	$I_D = 75\text{A}$
Q_{gs}	Gate-to-Source Charge	—	35	—	—	$V_{DS} = 50V$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	43	—	—	$V_{GS} = 10V$ ⑤
R_G	Gate Resistance	—	1.3	—	Ω	—
$t_{d(on)}$	Turn-On Delay Time	—	25	—	ns	$V_{DD} = 65V$
t_r	Rise Time	—	67	—	—	$I_D = 75\text{A}$
$t_{d(off)}$	Turn-Off Delay Time	—	78	—	—	$R_G = 2.6\Omega$
t_f	Fall Time	—	88	—	—	$V_{GS} = 10V$ ⑤
C_{iss}	Input Capacitance	—	9620	—	pF	$V_{GS} = 0V$
C_{oss}	Output Capacitance	—	670	—	—	$V_{DS} = 50V$
C_{rss}	Reverse Transfer Capacitance	—	250	—	—	$f = 1.0\text{MHz}$
C_{oss} eff. (ER)	Effective Output Capacitance (Energy Related) ⑦	—	820	—	—	$V_{GS} = 0V, V_{DS} = 0V \text{ to } 80V$ ⑧
C_{oss} eff. (TR)	Effective Output Capacitance (Time Related) ⑥	—	950	—	—	$V_{GS} = 0V, V_{DS} = 0V \text{ to } 80V$ ⑥

Diode Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	170①	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{SM}	Pulsed Source Current (Body Diode) ②⑦	—	—	670	—	—
V_{SD}	Diode Forward Voltage	—	—	1.3	V	$T_J = 25^\circ\text{C}, I_S = 75\text{A}, V_{GS} = 0V$ ⑤
t_{rr}	Reverse Recovery Time	—	50	75	ns	$T_J = 25^\circ\text{C}$ $V_R = 85V$,
		—	60	90	—	$T_J = 125^\circ\text{C}$ $I_F = 75\text{A}$
Q_{rr}	Reverse Recovery Charge	—	94	140	nC	$T_J = 25^\circ\text{C}$ $\text{di/dt} = 100\text{A}/\mu\text{s}$ ⑤
		—	140	210	—	$T_J = 125^\circ\text{C}$
I_{RRM}	Reverse Recovery Current	—	3.5	—	A	$T_J = 25^\circ\text{C}$
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

- ① Calculated continuous current based on maximum allowable junction temperature. Bond wire current limit is 120A. Note that current limitations arising from heating of the device leads may occur with some lead mounting arrangements.
- ② Repetitive rating; pulse width limited by max. junction temperature.
- ③ Limited by $T_{J\text{max}}$, starting $T_J = 25^\circ\text{C}$, $L = 0.033\text{mH}$
 $R_G = 25\Omega$, $I_{AS} = 108\text{A}$, $V_{GS} = 10V$. Part not recommended for use above this value.
- ④ $I_{SD} \leq 75\text{A}$, $\text{di/dt} \leq 630\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(\text{BR})\text{DSS}}$, $T_J \leq 175^\circ\text{C}$.
- ⑤ Pulse width $\leq 400\mu\text{s}$; duty cycle $\leq 2\%$.
- ⑥ C_{oss} eff. (TR) is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .
- ⑦ C_{oss} eff. (ER) is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .
- ⑧ When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994.
- ⑨ R_θ is measured at T_J approximately 90°C .

**Fig 1.** Typical Output Characteristics**Fig 2.** Typical Output Characteristics**Fig 3.** Typical Transfer Characteristics**Fig 4.** Normalized On-Resistance vs. Temperature**Fig 5.** Typical Capacitance vs. Drain-to-Source Voltage**Fig 6.** Typical Gate Charge vs. Gate-to-Source Voltage

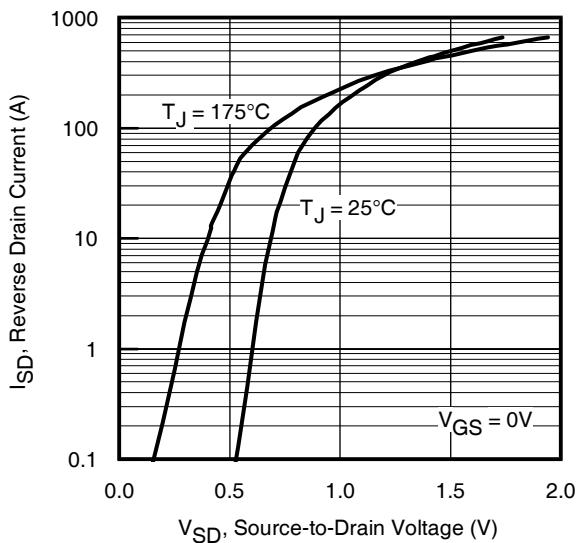


Fig 7. Typical Source-Drain Diode Forward Voltage

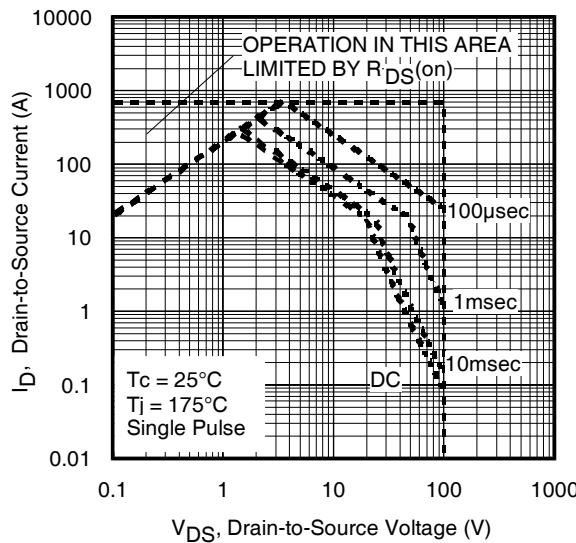


Fig 8. Maximum Safe Operating Area

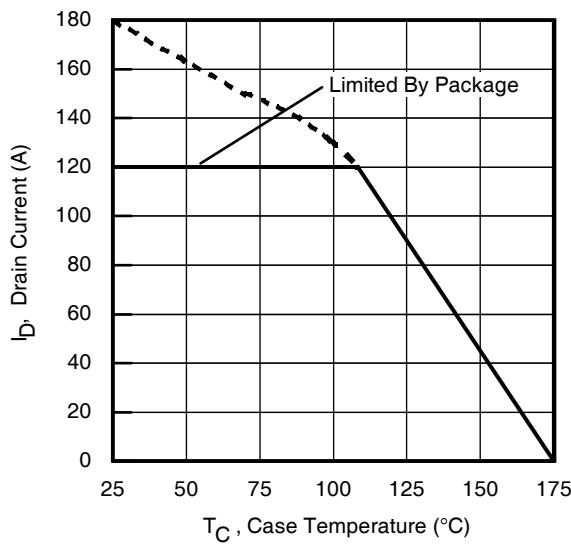


Fig 9. Maximum Drain Current vs. Case Temperature

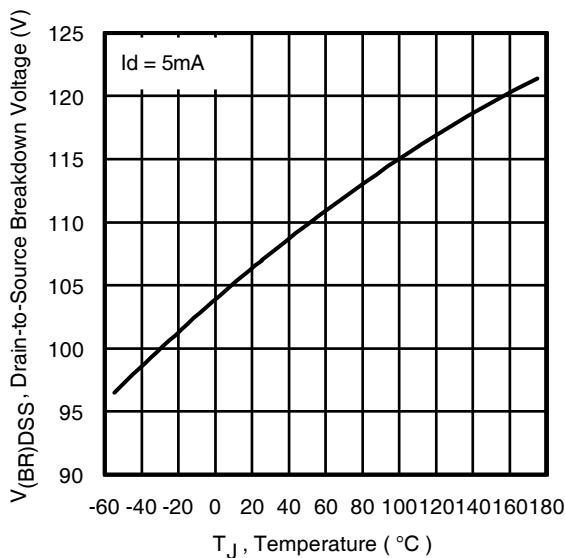


Fig 10. Drain-to-Source Breakdown Voltage

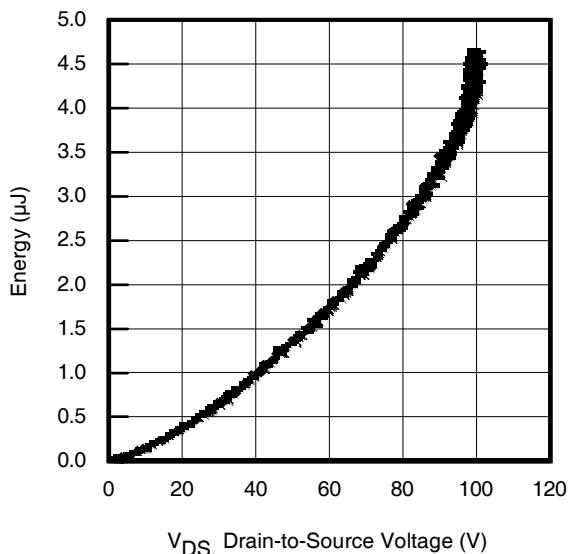


Fig 11. Typical C_{oss} Stored Energy

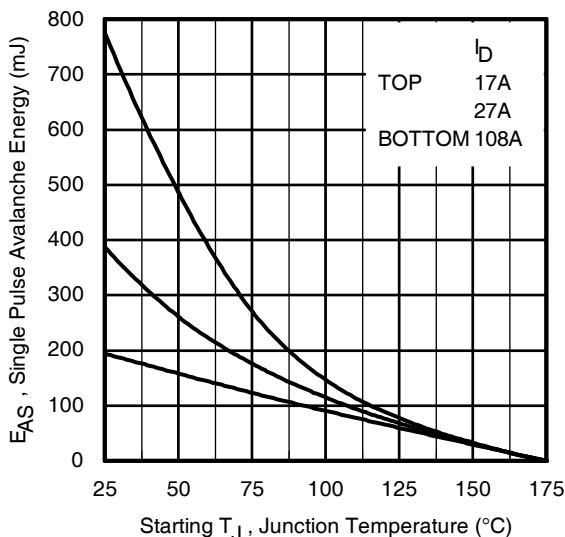


Fig 12. Maximum Avalanche Energy vs. Drain Current

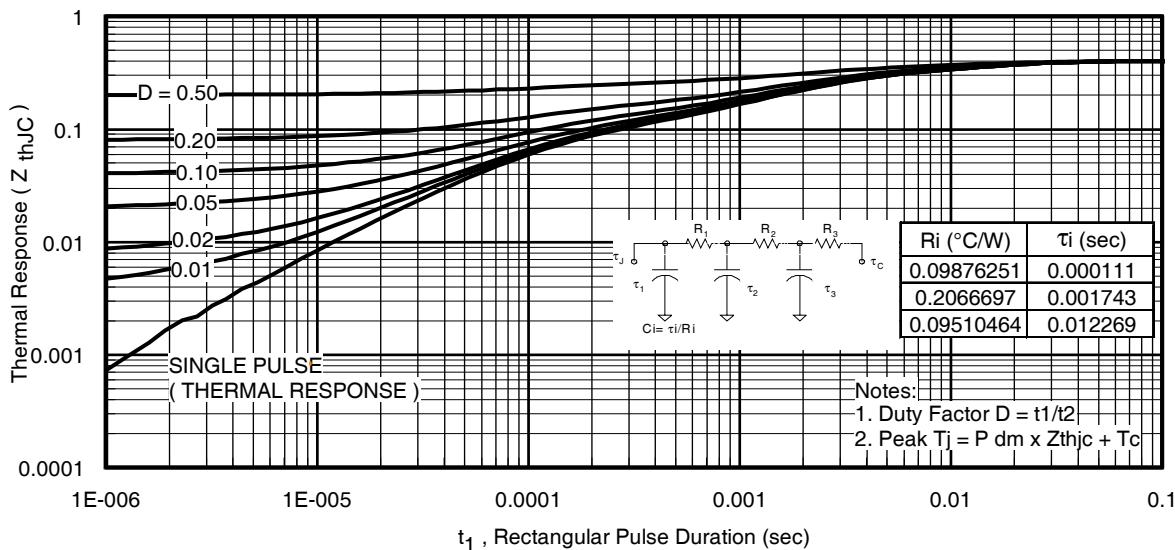


Fig 13. Maximum Effective Transient Thermal Impedance, Junction-to-Case

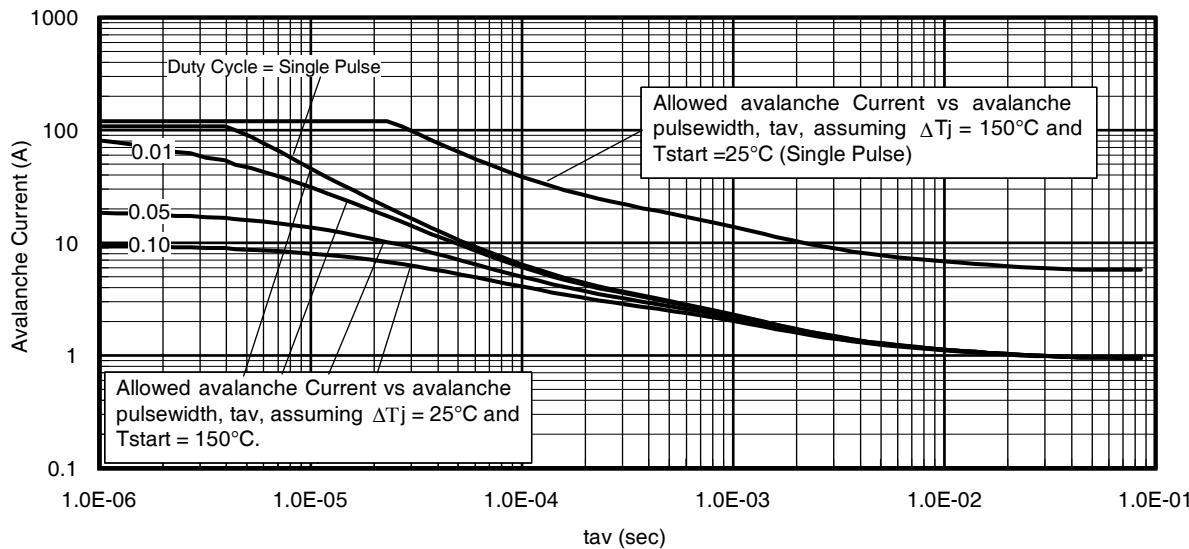
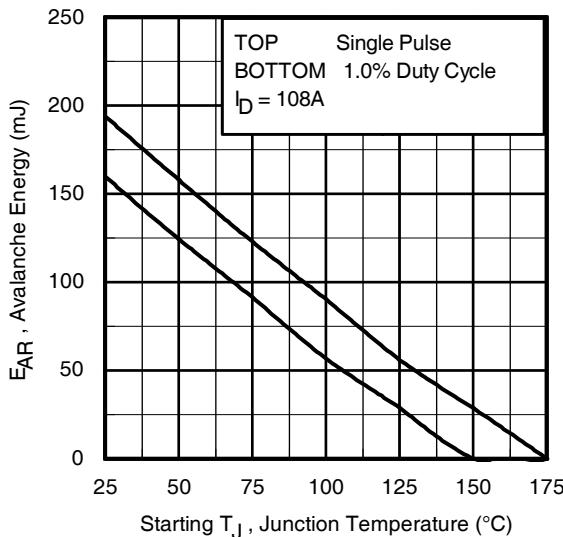


Fig 14. Typical Avalanche Current vs.Pulsewidth

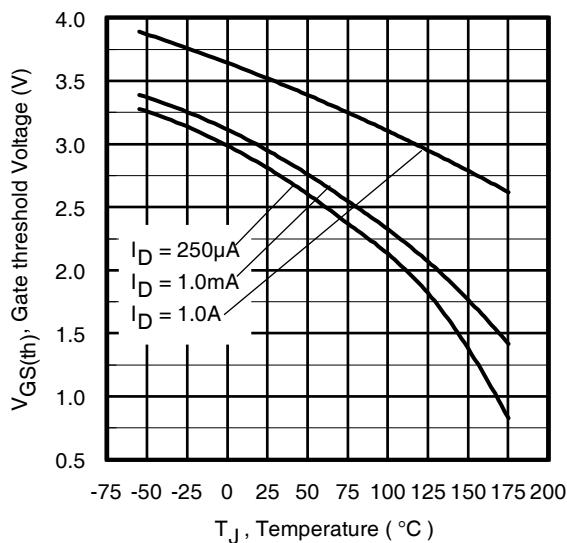
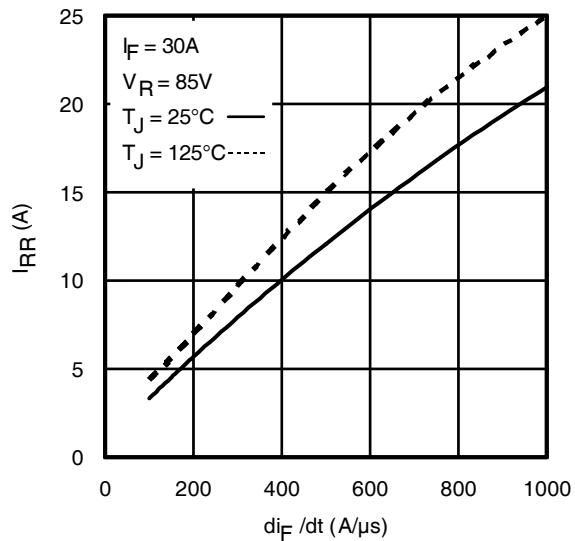
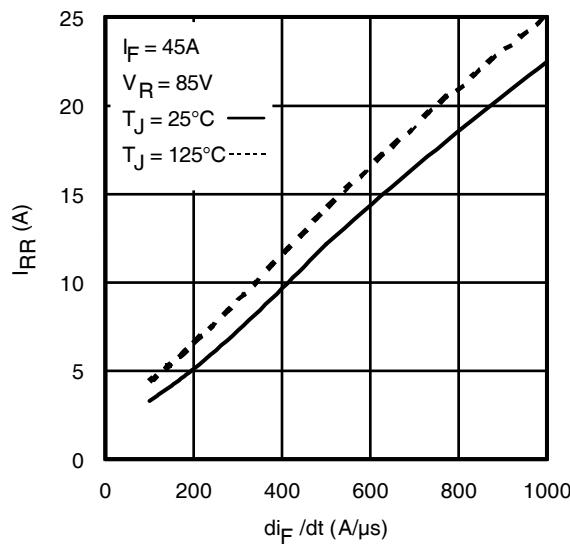
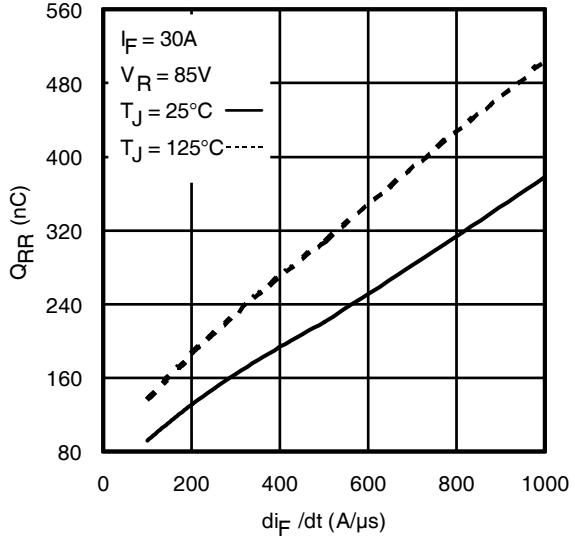
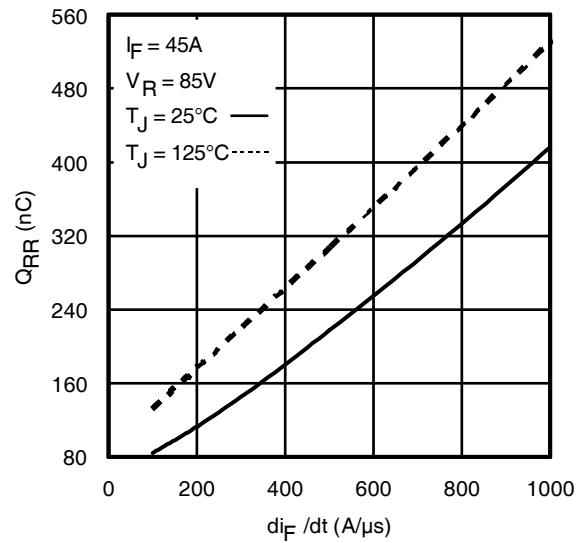


Notes on Repetitive Avalanche Curves , Figures 14, 15:
(For further info, see AN-1005 at www.irf.com)

1. Avalanche failures assumption:
Purely a thermal phenomenon and failure occurs at a temperature far in excess of T_{jmax} . This is validated for every part type.
 2. Safe operation in Avalanche is allowed as long as T_{jmax} is not exceeded.
 3. Equation below based on circuit and waveforms shown in Figures 16a, 16b.
 4. $P_{D(ave)}$ = Average power dissipation per single avalanche pulse.
 5. BV = Rated breakdown voltage (1.3 factor accounts for voltage increase during avalanche).
 6. I_{av} = Allowable avalanche current.
 7. ΔT = Allowable rise in junction temperature, not to exceed T_{jmax} (assumed as 25°C in Figure 14, 15).
- t_{av} = Average time in avalanche.
 D = Duty cycle in avalanche = $t_{av} \cdot f$
 $Z_{thJC}(D, t_{av})$ = Transient thermal resistance, see Figures 13)

$$\begin{aligned} P_{D(ave)} &= 1/2 (1.3 \cdot BV \cdot I_{av}) = \Delta T / Z_{thJC} \\ I_{av} &= 2\Delta T / [1.3 \cdot BV \cdot Z_{th}] \\ E_{AS(AR)} &= P_{D(ave)} \cdot t_{av} \end{aligned}$$

Fig 15. Maximum Avalanche Energy vs. Temperature

**Fig. 16.** Threshold Voltage vs. Temperature**Fig. 17 -** Typical Recovery Current vs. di_f/dt **Fig. 18 -** Typical Recovery Current vs. di_f/dt **Fig. 19 -** Typical Stored Charge vs. di_f/dt **Fig. 20 -** Typical Stored Charge vs. di_f/dt

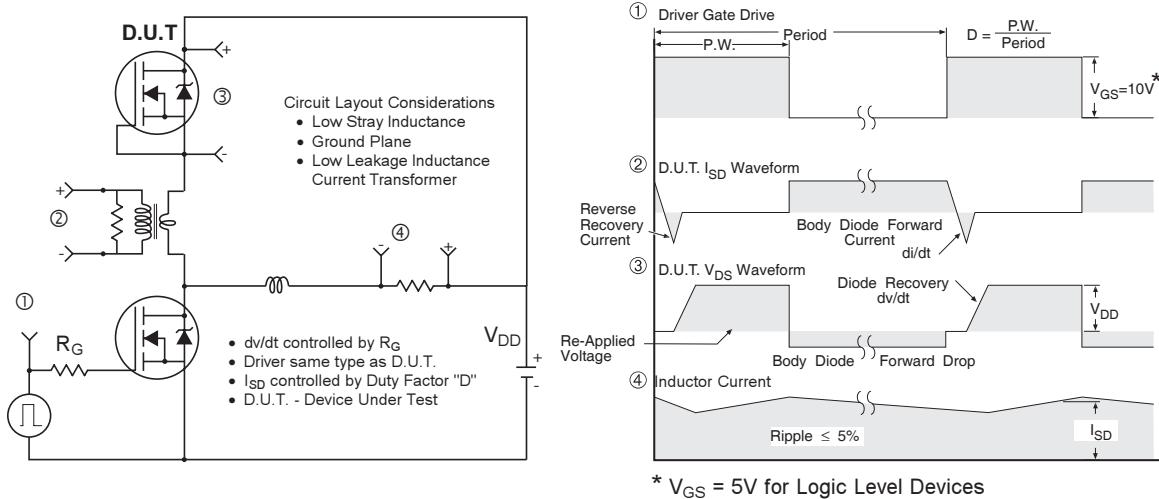


Fig 20. Peak Diode Recovery dv/dt Test Circuit for N-Channel HEXFET® Power MOSFETs

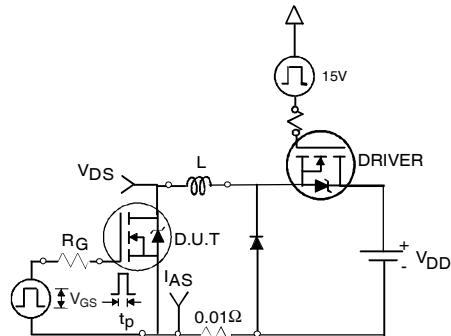


Fig 21a. Unclamped Inductive Test Circuit

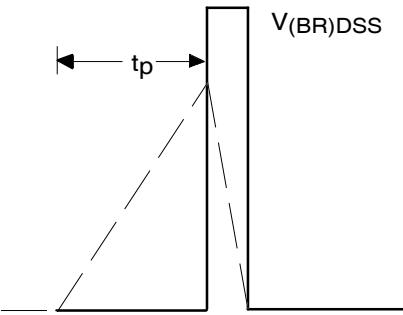


Fig 21b. Unclamped Inductive Waveforms

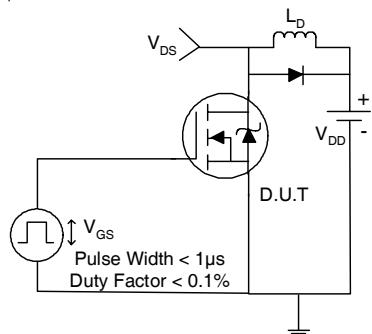


Fig 22a. Switching Time Test Circuit

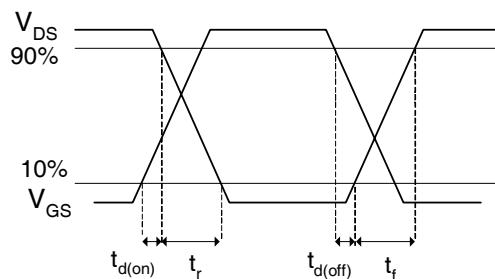


Fig 22b. Switching Time Waveforms

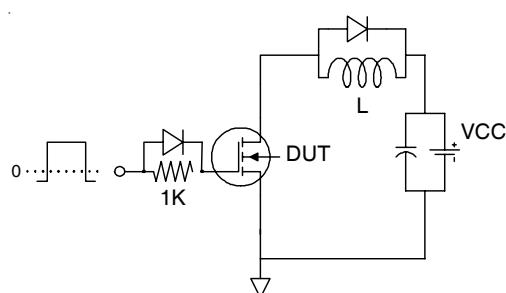


Fig 23a. Gate Charge Test Circuit

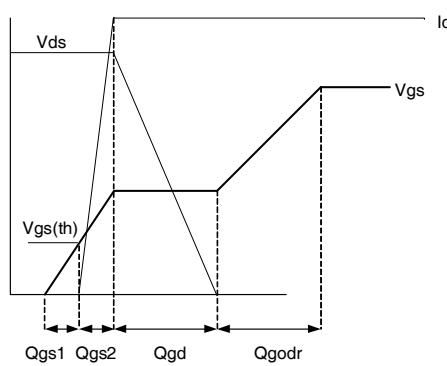
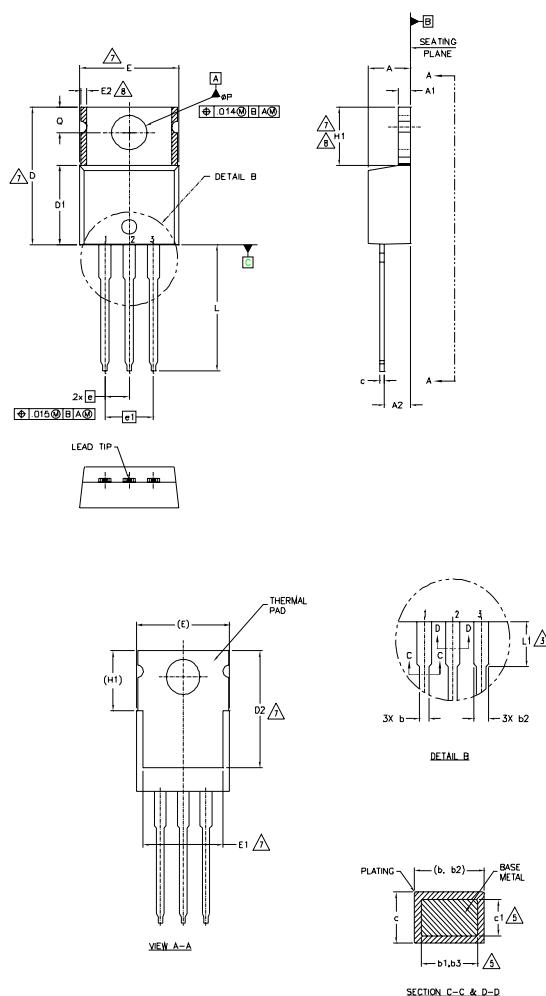


Fig 23b. Gate Charge Waveform

TO-220AB Package Outline

Dimensions are shown in millimeters (inches)



NOTES:

- 1.- DIMENSIONING AND TOLERANCING AS PER ASME Y14.5 M- 1994.
- 2.- DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS].
- 3.- LEAD DIMENSION AND FINISH UNCONTROLLED IN L1.
- 4.- DIMENSION D, D1 & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005" (.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTER MOST EXTREMES OF THE PLASTIC BODY.
- 5.- DIMENSION b1, b3 & c1 APPLY TO BASE METAL ONLY.
- 6.- CONTROLLING DIMENSION : INCHES.
- 7.- THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS E,H1,D2 & E1
- 8.- DIMENSION E2 X H1 DEFINE A ZONE WHERE STAMPING AND SINGULATION IRREGULARITIES ARE ALLOWED.
- 9.- OUTLINE CONFORMS TO JEDEC TO-220, EXCEPT A2 (max.) AND D2 (min.) WHERE DIMENSIONS ARE DERIVED FROM THE ACTUAL PACKAGE OUTLINE.

SYMBOL	DIMENSIONS				NOTES	
	MILLIMETERS		INCHES			
	MIN.	MAX.	MIN.	MAX.		
A	3.56	4.83	.140	.190		
A1	1.14	1.40	.045	.055		
A2	2.03	2.92	.080	.115		
b	0.38	1.01	.015	.040		
b1	0.38	0.97	.015	.038	5	
b2	1.14	1.78	.045	.070		
b3	1.14	1.73	.045	.068	5	
c	0.36	0.61	.014	.024		
c1	0.36	0.56	.014	.022	5	
D	14.22	16.51	.560	.650	4	
D1	8.38	9.02	.330	.355		
D2	11.68	12.88	.460	.507	7	
E	9.65	10.67	.380	.420	4,7	
E1	6.86	8.89	.270	.350	7	
E2	—	0.76	—	.030	8	
e	2.54 BSC		.100 BSC			
e1	5.08 BSC		.200 BSC			
H1	5.84	6.86	.230	.270	7,8	
L	12.70	14.73	.500	.580		
L1	3.56	4.06	.140	.160	3	
ΦP	3.54	4.08	.139	.161		
Q	2.54	3.42	.100	.135		

LEAD ASSIGNMENTS

HEXFET

- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE

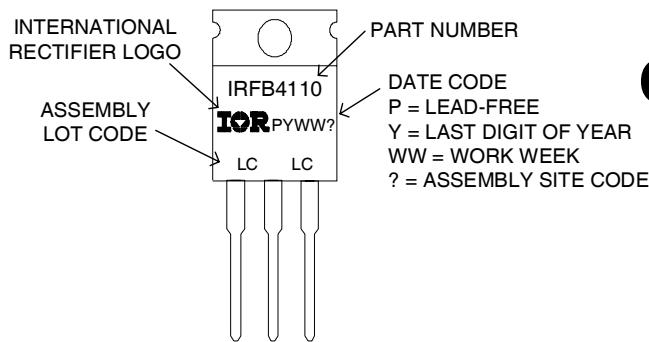
IGBTs, CoPACK

- 1.- GATE
- 2.- COLLECTOR
- 3.- Emitter

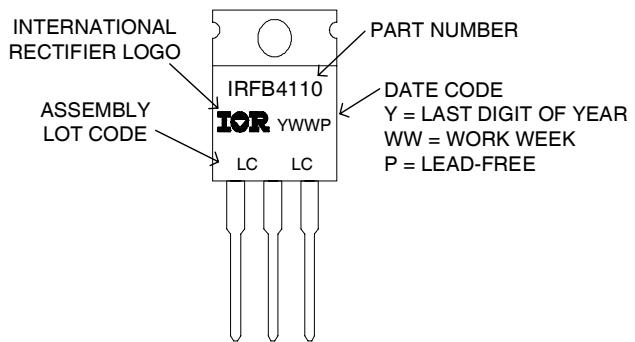
DIODES

- 1.- ANODE
- 2.- CATHODE
- 3.- ANODE

TO-220AB Part Marking Information



OR



TO-220AB packages are not recommended for Surface Mount Application.

Note: For the most current drawing please refer to IR website at: <http://www.irf.com/package/>

Qualification information[†]

Qualification level	Industrial [†]	
	(per JEDEC JESD47F ^{††} guidelines)	
Moisture Sensitivity Level	TO-220	N/A
RoHS compliant	Yes	

[†] Qualification standards can be found at International Rectifier's web site: <http://www.irf.com/product-info/reliability/>

^{††} Applicable version of JEDEC standard at the time of product release.

Revision History

Date	Comment
4/28/2014	<ul style="list-style-type: none">• Updated data sheet with new IR corporate template.• Updated package outline & part marking on page 8.• Added bullet point in the Benefits "RoHS Compliant, Halogen -Free" on page 1.• Updated typo on the Fig.19 and Fig.20, unit of Y-axis from "A" to "nC" on page 6.

International
Rectifier
IR

IR WORLD HEADQUARTERS: 101 N. Sepulveda Blvd., El Segundo, California 90245, USA
To contact International Rectifier, please visit <http://www.irf.com/whoto-call/>

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